

Amendments to the Specification

Please replace the paragraph beginning on page 7, line 18 with the following amended paragraph:

Fig. 13 is a cross-sectional view of the semiconductor device 1 according to the third embodiment of the present invention; [[and]]

Please replace the paragraph beginning on page 7, line 21 with the following amended paragraph:

Fig. 14 is a view for describing wire bonding employed in the semiconductor device 1 according to the third embodiment of the present invention[[.]]; and

Please insert the following new paragraph on page 7, between line 23 and the heading "Detailed Description of the Invention":

Fig. 15 is a plan view of another embodiment of the present invention.